

Page 3, before line 7, insert the following heading:

A2 --Summary of the Invention--

Page 8, before line 1, insert the following heading:

A3 --Brief Description of the Drawings--

Page 9, before line 8, insert the following heading:

A4 --Description of the Invention--

Add the following Abstract:

A5 --A method for making a device, such as a smart card, of the type having a support associated with at least a microcircuit in the form of a chip. First, an assembly is provided that constitutes a thin chip maintained by a first surface integral with a substrate, and having on an opposite second surface at least a bond pad. On a surface of the support, a communication interface is formed that includes at least a connecting element with the chip. The assembly having the chip and the substrate is placed against the communication interface, with at least a bond pad of the chip positioned against a corresponding connection element of the communication interface. Each pad is integrated with its respective connection element. The substrate is then removed from the first surface of the chip. The method advantageously uses SOI chip technology.--